# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

Compaq Presario SR5700 PC Series

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm (Mainboard, power supply, 2*memory, add-on card)</td>
<td>5</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries (Mainboard)</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power supply</td>
<td>4</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>(System and PSU fans)</td>
<td>2</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components and waste containing asbestos | 0
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cross screwdriver</td>
<td></td>
</tr>
<tr>
<td>Wire cutters</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unfix system side cover screw*1 then remove side cover.
2. Remove front panel from system.
3. Displug all cable connector from motherboard and all devices.
4. Unfix front IO cable screw*1 then remove it.
5. Unfix card reader screw*1 then remove it.
6. Unfix PSU screw*4 then remove it.
7. Unfix system fan screw*4 then remove it.
8. Unfix H/S screw*4 then remove it from MB
9. Unfix MB screw*8 then remove it from chassis.
10. 
11. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove side cover

1. Unfix thumbscrew 1pcs.
2. Remove side cover.
2. Remove main bezel

1. Release main bezel hook 1, 2, 3.
2. Take out main bezel.
3. Unplug all cable

Unplug:

1. Power cable (24pin)
2. Heat Sink fan cable
3. 12V power cable (4pin)
4. Audio cable
5. Front USB, card reader and switch cable
6. HDD data and power cable
7. ODD data and power cable
4. Remove front I/O

1. Unfix 1 screw from chassis.
2. Remove front I/O cable.

5. Remove card reader

1. Unfix 1 screw from chassis.
2. Remove card reader from chassis.
6. Remove PSU

1. Unfix 4 screw from chassis.
2. Remove card reader from chassis.

FIGURE 1. Screwed off the screws & cut out the cable tie

FIGURE 2. Screwed off the screws
FIGURE 3. Pull out the metal cover

FIGURE 4. Screwed off the screws & remove PCBA
FIGURE 5. Screwed off the screws & remove the small PCBA

FIGURE 6. Remove the electrolytic capacitors
7. Remove system fan

Unfix 4 screw and remove system fan from chassis.
Remove Add-on card

1. Unfix 1 screw and remove fixed bracket.
2. Press lock.
3. Unplug VGA card.
Remove MB

1. Unfix 8 screws from MB.
2. Remove MB from chassis.

Remove coin battery from MB